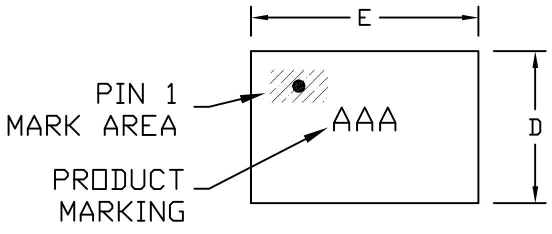


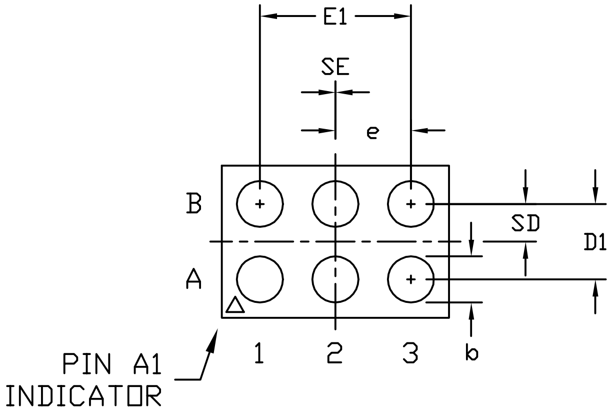
TOP VIEW

COMMON DIMENSIONS	
A	0.62+0.05−0.08
A1	0.29±0.02
A2	0.33 REF.
b	ø0.35±0.03
D1	0.50 BASIC
E1	1.00 BASIC
e	0.50 BASIC
SD	0.25 BASIC
SE	0.00 BASIC

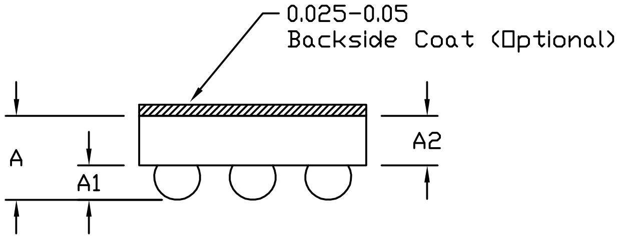
PKG. CODE	VARIABLE DIMENSIONS		DEPOPULATED SOLDER BALLS
	D	E	
B6-1	1.00±0.05	1.52±0.05	NONE
B6-2	1.00±0.05	1.52±0.05	B2
B6-3	1.05±0.05	1.57±0.05	NONE
B6-4	1.05±0.05	1.57±0.05	B2
B6-5	0.97±0.05	1.46±0.05	NONE
B6-6	1.16±0.05	1.57±0.05	NONE

NOTES:

1. All dimensions in millimeters.
2. Outer dimension (D & E) is defined by center lines between scribe lines.
3. Marking shown is for package orientation reference only. Number of characters and lines vary per product.
4. All dimensions are applicable to Leaded (−), PbFree (+), and MaxFilm parts/pkg codes.



BOTTOM VIEW



SIDE VIEW

TITLE:
PACKAGE OUTLINE,
6 BUMPS, 3X2 ARRAY, UCSP (B) PKG.

APPROVAL
DOCUMENT CONTROL NO.
21-0097
REV.
H
1/1

−DRAWING NOT TO SCALE−